



Product Overview

Focus Tech ME-500

Copper Microetch

Product Description

ME-500 is a concentrated microetch additive designed to improve the performance and stability of generic hydrogen peroxide/sulfuric acid microetches. ME-500's hydrogen peroxide stabilizers virtually eliminate destabilization losses. Etch accelerators and modifiers increase etch rate and improve surface topography. The result is a superior surface and improved performance for all processes requiring a microetch at remarkably low operating costs.

Features

- ⊙ Completely stabilizes hydrogen peroxide in the presence of metal ions even at elevated temperatures
- ⊙ Rate enhancing additives
- ⊙ Etch modifiers

Benefits

- ⊙ Reduces operating cost through decreased consumption
- ⊙ Increases etch rate without increasing consumption
- ⊙ Improves surface topography for increased coverage and adhesion in subsequent processes

Physical Properties

Specific gravity: 1.02
pH: 6-8
Appearance: clear to amber color
Freezing point: <40 °F

Operating Parameters

Copper loading: 3 – 7 oz/gal (22.5 – 52.5 g/L)
Hydrogen peroxide concentration: 3% – 6% (as 50% hydrogen peroxide)
4.3% - 8.6% (as 35% hydrogen peroxide)
Sulfuric acid concentration: 5% – 10%
Temperature: 80 °F – 100 °F

Safety

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

The information and recommendations, contained herein, regarding this product are, to the best of our knowledge, true and accurate. We make no guarantee of results because the conditions of actual use are beyond our control. We assume no liability for damages or penalties resulting from the use of this product or following our recommendations. Our recommendations and suggestions for use of this product are not intended to grant license to operate under or infringe any patent.